Abstract

This invention relates to a device for bonding of a second substrate (5) onto a first substrate (2) with the following features:

- a receiving apparatus (1) for receiving the first substrate (2) which has been coated with a bond layer (3) and the second substrate (5) which is held on the bond layer (3),
- an action apparatus for applying a bond force to the second substrate (5) on one action side (5o) of the second substrate (5), which side faces away from the bond layer (3) proceeding from an initial zone A which lies within an edge zone R of the action side (5o) as far as action on the entire action side (5o).

Furthermore this invention relates to a corresponding method.

Figure 4 in this respect